

AMENDMENTS TO THE CLAIMS

1. (Currently Amended) A process for manufacturing macroelectronics comprising the steps of:

producing thin film active electronics on separate carrier ~~substrates~~; substrates, wherein at least one of the carrier substrates is flexible; and

combining said substrates using anisotropic electrical conductors or light guides.

2. (Original) The process of claim 1 wherein one of said substrates is a flexible foil.
3. (Original) The process of claim 1 wherein one of said substrates is a rigid plate.
4. (Original) The process of claim 2 wherein the material for one of said substrates is plastic.
5. (Original) The process of claim 3 wherein the material for one of said substrates is plastic.
6. (Original) The process of claim 2 wherein the material for one of said substrates is glass.
7. (Original) The process of claim 3 wherein the material for one of said substrates is glass.
8. (Original) The process of claim 2 wherein the material for one of said substrates is metal.
9. (Original) The process of claim 3 wherein the material for one of said substrates is metal.

10. (Original) The process of claim 1 wherein the thin film active electronics are produced continuously on separate carrier substrates.
11. (Original) The process of claim 4 wherein organic light emitting diodes are formed on the plastic substrate.
12. (Original) The process of claim 5 wherein organic light emitting diodes are formed on the plastic substrate.
13. (Original) The process of claim 6 wherein organic light emitting diodes are formed on the glass substrate.
14. (Original) The process of claim 7 wherein organic light emitting diodes are formed on the glass substrate.
15. (Original) The process of claim 6 wherein thin film transistors are formed on the glass substrate.
16. (Original) The process of claim 7 wherein thin film transistors are formed on the glass substrate.

17. (Currently Amended) A process of making electronic circuits comprising the steps of:

forming at least two active circuits on separate carrier ~~substrates~~; substrates, wherein at least one of the carrier substrates is flexible, and

combining said active circuits by connecting them with a material which conducts in a direction perpendicular to the separate carrier substrates.

18. (Original) A method of manufacturing an electronic display comprising the steps of:

depositing a transparent conductor on a transparent substrate;

forming a thin film organic light emitting diode circuit on said transparent conductor;

forming a thin film transistor circuit; and

laminating said circuits to each other.

19. (Original) The method of claim 18 wherein said laminating step uses an adhesive anisotropic conductor.

20. (Original) The method of claim 19 wherein the conductor is an electrical or optical conductor.

21. (Original) The method of claim 19 wherein the bonding layer is the conductor.
22. (Currently Amended) A method of manufacturing an electronic circuit comprising the steps of:
- forming a first active circuit on a first flexible plane;
- forming a second active circuit on a second flexible plane; and
- co-laminating said first and second planes with an anisotropic conductor in between.
23. (Original) The process of claim 4, wherein the thin film active electronics comprise thin film transistors.
24. (Original) The process of claim 8, wherein the metal comprises steel.
25. (Original) The process of claim 24, wherein the thin film active electronics comprise organic light emitting diodes.

26. (New) A process for manufacturing macroelectronics comprising the steps of:

producing thin film active electronics on separate carrier substrates;

positioning the active electronics of the carrier substrates in facing relation with respect to each other; and

combining said substrates using anisotropic electrical conductors or light guides.

27. (New) The process of claim 26, wherein one of said substrates is a flexible foil.

28. (New) The process of claim 26, wherein one of said substrates is a rigid plate.

29. (New) The process of claim 27, wherein the material for one of said substrates is plastic.

30. (New) The process of claim 28, wherein the material for one of said substrates is plastic.

31. (New) The process of claim 27, wherein the material for one of said substrates is glass.

32. (New) The process of claim 28, wherein the material for one of said substrates is glass.

33. (New) The process of claim 27, wherein the material for one of said substrates is metal.

34. (New) The process of claim 28, wherein the material for one of said substrates is metal.
35. (New) The process of claim 26, wherein the thin film active electronics are produced continuously on separate carrier substrates.
36. (New) The process of claim 29, wherein organic light emitting diodes are formed on the plastic substrate.
37. (New) The process of claim 30, wherein organic light emitting diodes are formed on the plastic substrate.
38. (New) The process of claim 29, wherein organic light emitting diodes are formed on the glass substrate.
39. (New) The process of claim 30, wherein organic light emitting diodes are formed on the glass substrate.
40. (New) The process of claim 29, wherein thin film transistors are formed on the glass substrate.
41. (New) The process of claim 30, wherein thin film transistors are formed on the glass substrate.